Electrical Rules Check Report

Class	Document	Message
		Successful Compile for 24-12V_3A_TPS62933.PrjPcb

9 2023 6:47:38 PN₁ Page 1 of 1

Design Rules Verification ReportFilename: D:\EE\BMS\24-12V_3A_TPS62933\Converter.PcbDoc

Warnings 0 Rule Violations 8

Warnings	
Total	0

Rule Violations	
Clearance Constraint (Gap=0.254mm) (All),(All)	0
Short-Circuit Constraint (Allowed=No) (All),(All)	0
Un-Routed Net Constraint ((All))	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=0.127mm) (Max=0.384mm) (Preferred=0.254mm) (InNetClass('All Nets'))	0
Width Constraint (Min=0.254mm) (Max=1.143mm) (Preferred=0.254mm) (InNetClass('Power'))	0
SMD To Plane Constraint (Distance=0mm) (All)	0
SMD Neck-Down Constraint (Percent=95%) (All)	1
Power Plane Connect Rule(Direct Connect)(Expansion=0.508mm) (Conductor Width=0.254mm) (Air Gap=0.254mm)	0
Minimum Annular Ring (Minimum=0.13mm) (All)	0
Hole Size Constraint (Min=0.3mm) (Max=6.3mm) (All)	0
Hole To Hole Clearance (Gap=0.6mm) (All),(All)	0
Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)	7
Silk To Solder Mask (Clearance=0.15mm) (IsPad),(All)	0
Silk to Silk (Clearance=0.127mm) (AII), (AII)	0
Net Antennae (Tolerance=0mm) (All)	0
Board Clearance Constraint (Gap=0mm) (All)	0
Height Constraint (Min=0mm) (Max=25.4mm) (Prefered=12.7mm) (All)	0
Total	8

SMD Neck-Down Constraint (Percent=95%) (All)

SMD Neck-Down Constraint: Between Pad C6-2(35mm,8.45mm) on Top Layer And Track (34.1mm,8.45mm) (35mm,8.45mm) on Top Layer Relative Track Width: 112.06%

Page 1 of 2 9 2023 6:47:40 PN

Minimum Solder Mask Sliver (Cap=0.254mm) (All),(All) Minimum Solder Mask Sliver Constraint: (0.124mm < 0.254mm) Between Pad B1-1(11mm,5.5mm) on Top Layer And Pad B1-2(11mm,5mm) on Top Layer [Top Solder] Mask Sliver [0.124mm] Minimum Solder Mask Sliver Constraint: (0.124mm < 0.254mm) Between Pad B1-2(11mm,5mm) on Top Layer And Pad B1-3(11mm,4.5mm) on Top Layer [Top Solder] Mask Sliver [0.124mm] Minimum Solder Mask Sliver Constraint: (0.124mm < 0.254mm) Between Pad B1-3(11mm,4.5mm) on Top Layer And Pad B1-4(11mm,4mm) on Top Layer [Top Solder] Mask Sliver [0.124mm] Minimum Solder Mask Sliver Constraint: (0.124mm < 0.254mm) Between Pad B1-5(12.676mm,4mm) on Top Layer And Pad B1-6(12.676mm,4.5mm) on Top Layer [Top Solder] Mask Sliver [0.175mm] Minimum Solder Mask Sliver Constraint: (0.124mm < 0.254mm) Between Pad B1-5(12.676mm,4.5mm) on Top Layer And Pad B1-7(12.676mm,5mm) on Top Layer [Top Solder] Mask Sliver [0.124mm] Minimum Solder Mask Sliver Constraint: (0.124mm < 0.254mm) Between Pad B1-6(12.676mm,4.5mm) on Top Layer And Pad B1-7(12.676mm,5mm) on Top Layer [Top Solder] Mask Sliver [0.124mm] Minimum Solder Mask Sliver Constraint: (0.124mm < 0.254mm) Between Pad B1-7(12.676mm,5mm) on Top Layer And Pad B1-8(12.676mm,5.5mm) on Top Layer [Top Solder] Mask Sliver [0.124mm] Minimum Solder Mask Sliver Constraint: (0.124mm < 0.254mm) Between Pad B1-7(12.676mm,5mm) on Top Layer And Pad B1-8(12.676mm,5.5mm) on Top Layer [Top Solder] Mask Sliver [0.124mm]

9 2023 6:47:40 PN